# Octal D-Type Flip-Flop with 3-State Output

The MC74VHCT374A is an advanced high speed CMOS octal flip-flop with 3-state output fabricated with silicon gate CMOS technology. It achieves high speed operation similar to equivalent Bipolar Schottky TTL while maintaining CMOS low power dissipation.

This 8-bit D-type flip-flop is controlled by a clock input and an output enable input. When the output enable input is high, the eight outputs are in a high impedance state.

The internal circuit is composed of three stages, including a buffer output which provides high noise immunity and stable output.

The VHCT inputs are compatible with TTL levels. This device can be used as a level converter for interfacing 3.3 V to 5.0 V, because it has full 5.0 V CMOS level output swings.

The VHCT374A input and output (when disabled) structures provide protection when voltages between 0 V and 5.5 V are applied, regardless of the supply voltage. These input and output structures help prevent device destruction caused by supply voltage—input/output voltage mismatch, battery backup, hot insertion, etc.

## **Features**

- High Speed:  $f_{max} = 140 \text{ MHz}$  (Typ) at  $V_{CC} = 5.0 \text{ V}$
- Low Power Dissipation:  $I_{CC} = 4 \mu A$  (Max) at  $T_A = 25^{\circ}C$
- TTL-Compatible Inputs:  $V_{IL} = 0.8 \text{ V}$ ;  $V_{IH} = 2.0 \text{ V}$
- Power Down Protection Provided on Inputs and Outputs
- Balanced Propagation Delays
- Designed for 4.5 V to 5.5 V Operating Range
- Low Noise: V<sub>OLP</sub> = 1.6 V (Max)
- Pin and Function Compatible with Other Standard Logic Families
- Latchup Performance Exceeds 300 mA
- ESD Performance:

Human Body Model > 2000 V; Machine Model > 200 V

- Chip Complexity: 276 FETs or 69 Equivalent Gates
- These Devices are Pb-Free and are RoHS Compliant

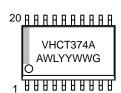


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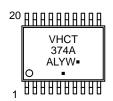
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## MARKING DIAGRAMS









A = Assembly Location

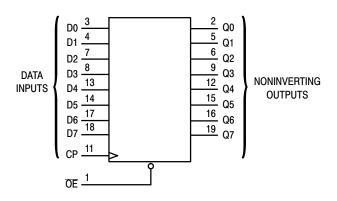
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G or = = Pb-Free Package
(Note: Microdot may be in either location)

#### **FUNCTION TABLE**

	INPUTS	OUTPUT	
ŌĒ	СР	D	q
L L L		H L X	H L No Change Z

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.





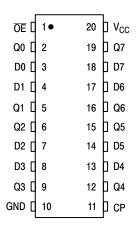


Figure 2. Pin Assignment

#### **MAXIMUM RATINGS**

Symbol	Paramete	7	Value	Unit
V <sub>CC</sub>	DC Supply Voltage	DC Supply Voltage		
V <sub>in</sub>	DC Input Voltage		- 0.5 to + 7.0	V
V <sub>out</sub>	DC Output Voltage	Outputs in 3–State High or Low State	- 0.5 to + 7.0 - 0.5 to V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input Diode Current		- 20	mA
lok	Output Diode Current (V <sub>OUT</sub> < 0	± 20	mA	
l <sub>out</sub>	DC Output Current, per Pin		± 25	mA
Icc	DC Supply Current, V <sub>CC</sub> and G	ND Pins	± 75	mA
P <sub>D</sub>	Power Dissipation in Still Air,	SOIC Package† TSSOP Package†	500 450	mW
T <sub>stg</sub>	Storage Temperature		- 65 to + 150	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range GND  $\leq$  ( $V_{in}$  or  $V_{out}$ )  $\leq$   $V_{CC}$ .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or  $V_{CC}$ ). Unused outputs must be left open.

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

†Derating – SOIC Packages: – 7 mW/°C from 65° to 125°C TSSOP Package: – 6.1 mW/°C from 65° to 125°C

## **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	DC Supply Voltage	4.5	5.5	V
V <sub>in</sub>	DC Input Voltage	0	5.5	V
V <sub>out</sub>	DC Output Voltage Outputs in 3–State High or Low State	0	5.5 V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature	- 40	+ 85	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time V <sub>CC</sub> =5.0V ±0.5V	0	20	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

## DC ELECTRICAL CHARACTERISTICS

			V <sub>CC</sub>		T <sub>A</sub> = 25	°C	T <sub>A</sub> = - 40	0 to 85°C	
Symbol	Parameter	Test Conditions	v	Min	Тур	Max	Min	Max	Unit
V <sub>IH</sub>	Minimum High-Level Input Voltage		4.5 to 5.5	2.0			2.0		V
V <sub>IL</sub>	Maximum Low-Level Input Voltage		4.5 to 5.5			0.8		0.8	V
V <sub>OH</sub>	Minimum High-Level Output	I <sub>OH</sub> = - 50μA	4.5	4.4	4.5		4.4		V
	Voltage $V_{in} = V_{IH}$ or $V_{IL}$	I <sub>OH</sub> = - 8mA	4.5	3.94			3.80		
V <sub>OL</sub>	Maximum Low-Level Output	I <sub>OL</sub> = 50μA	4.5		0.0	0.1		0.1	V
	Voltage $V_{in} = V_{IH}$ or $V_{IL}$	I <sub>OL</sub> = 8mA	4.5			0.36		0.44	
l <sub>in</sub>	Maximum Input Leakage Current	V <sub>in</sub> = 5.5 V or GND	0 to 5.5			± 0.1		± 1.0	μΑ
I <sub>OZ</sub>	Maximum 3–State Leakage Current	$V_{in} = V_{IL} \text{ or } V_{IH}$ $V_{out} = V_{CC} \text{ or GND}$	5.5			± 0.25		± 2.5	μА
I <sub>CC</sub>	Maximum Quiescent Supply Current	V <sub>in</sub> = V <sub>CC</sub> or GND	5.5			4.0		40.0	μΑ
I <sub>CCT</sub>	Quiescent Supply Current	Per Input: V <sub>IN</sub> = 3.4V Other Input: V <sub>CC</sub> or GND	5.5			1.35		1.50	mA
I <sub>OPD</sub>	Output Leakage Current	V <sub>OUT</sub> = 5.5V	0			0.5		5.0	μΑ

## AC ELECTRICAL CHARACTERISTICS (Input $t_f = t_f = 3.0 \text{ns}$ )

				T <sub>A</sub> = 25	°C	$T_A = -40$	to 85°C	
Symbol	Parameter	Test Conditions	Min	Тур	Max	Min	Max	Unit
f <sub>max</sub>	Maximum Clock Frequency (50% Duty Cycle)	$V_{CC} = 5.0 \pm 0.5 V$ $C_L = 15 pF$ $C_L = 50 pF$	90 85	140 130		80 95		MHz
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, CP to Q	$V_{CC} = 5.0 \pm 0.5 V$ $C_L = 15 pF$ $C_L = 50 pF$		4.1 5.6	9.4 10.4	1.0 1.0	10.5 11.5	ns
t <sub>PZL</sub> , t <sub>PZH</sub>	Output Enable Time, OE to Q	$V_{CC} = 5.0 \pm 0.5 V$ $C_{L} = 15 pF$ $R_{L} = 1 k \Omega$ $C_{L} = 50 pF$		6.5 7.3	10.2 11.2	1.0 1.0	11.5 12.5	ns
t <sub>PLZ</sub> , t <sub>PHZ</sub>	Output Disable Time OE to Q	$\begin{aligned} &V_{CC} = 5.0 \pm 0.5 V & C_L = 50 pF \\ &R_L = 1 k \Omega \end{aligned}$		7.0	11.2	1.0	12.0	ns
toslh, toshl	Output to Output Skew	$V_{CC} = 5.0 \pm 0.5 V$ $C_L = 50 pF$ (Note 1)			1.0		1.0	ns
C <sub>in</sub>	Maximum Input Capacitance			4	10		10	pF
C <sub>out</sub>	Maximum 3–State Output Capacitance (Output in High–Impedance State)			9				pF

		Typical @ 25°C, V <sub>CC</sub> = 5.0V	
$C_{PD}$	Power Dissipation Capacitance (Note 2)	25	рF

## **NOISE CHARACTERISTICS** (Input $t_r = t_f = 3.0 \text{ns}$ , $C_L = 50 \text{pF}$ , $V_{CC} = 5.0 \text{V}$ )

			T <sub>A</sub> = 25°C	
Symbol	Parameter	Тур	Max	Unit
V <sub>OLP</sub>	Quiet Output Maximum Dynamic V <sub>OL</sub>	1.2	1.6	V
V <sub>OLV</sub>	Quiet Output Minimum Dynamic V <sub>OL</sub>		-1.6	V
$V_{IHD}$	V <sub>IHD</sub> Minimum High Level Dynamic Input Voltage		2.0	V
V <sub>ILD</sub>	Maximum Low Level Dynamic Input Voltage		0.8	V

## **TIMING REQUIREMENTS** (Input $t_f = t_f = 3.0 \text{ns}$ )

			T <sub>A</sub> =	25°C	T <sub>A</sub> = - 40 to 85°C	
Symbol	Parameter	Test Conditions	Тур	Limit	Limit	Unit
t <sub>w</sub>	Minimum Pulse Width, CP	$V_{CC} = 5.0 \pm 0.5 \text{ V}$		6.5	8.5	ns
t <sub>su</sub>	Minimum Setup Time, D to CP	$V_{CC} = 5.0 \pm 0.5 \text{ V}$		2.5	2.5	ns
t <sub>h</sub>	Minimum Hold Time, D to CP	$V_{CC} = 5.0 \pm 0.5 \text{ V}$		2.5	2.5	ns

Parameter guaranteed by design. t<sub>OSLH</sub> = |t<sub>PLHm</sub> - t<sub>PLHn</sub>|, t<sub>OSHL</sub> = |t<sub>PHLm</sub> - t<sub>PHLn</sub>|.
 C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I<sub>CC(OPR)</sub> = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>in</sub> + I<sub>CC</sub>/8 (per flip-flop). C<sub>PD</sub> is used to determine the no–load dynamic power consumption; P<sub>D</sub> = C<sub>PD</sub> • V<sub>CC</sub><sup>2</sup> • f<sub>in</sub> + I<sub>CC</sub> • V<sub>CC</sub>.

## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MC74VHCT374ADWRG	SOIC-20WB (Pb-Free)	1000 / Tape & Reel
MC74VHCT374ADTRG	TSSOP-20 (Pb-Free)	2500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

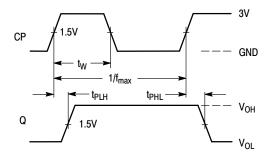


Figure 3. Switching Waveform

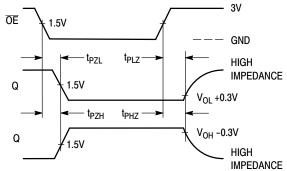


Figure 4. Switching Waveform

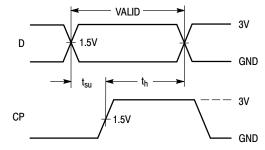
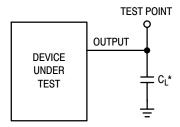
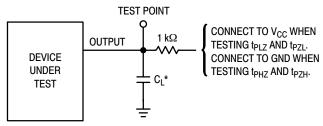


Figure 5. Switching Waveform



\*Includes all probe and jig capacitance

Figure 6. Test Circuit



\*Includes all probe and jig capacitance

Figure 7. Test Circuit

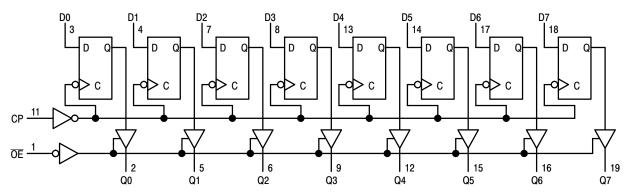
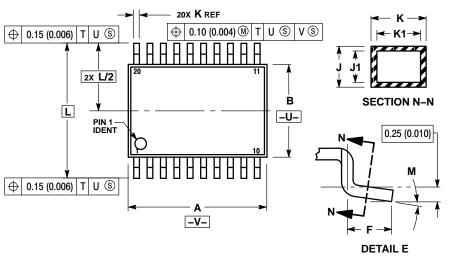
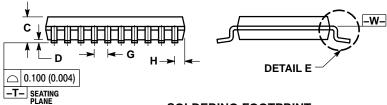


Figure 8. Expanded Logic Diagram

#### PACKAGE DIMENSIONS

## TSSOP-20 CASE 948E-02 **ISSUE C**





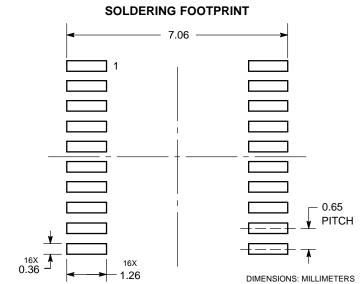
#### NOTES:

- DTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

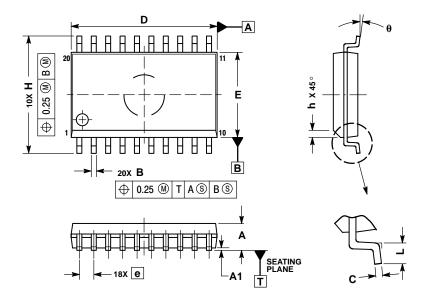
  2. CONTROLLING DIMENSION:
  MILLIMETER.
  3. DIMENSION A DOES NOT INCLUDE
  MOLD FLASH, PROTRUSIONS OR GATE
  BURRS. MOLD FLASH OR GATE BURRS
  SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  4. DIMENSION B DOES NOT INCLUDE
  INTER! EAD EI ASH OR PROTRUSION
- INTERLEAD FLASH OR PROTRUSION.
  INTERLEAD FLASH OR PROTRUSION
- INTERLEAD FLASH OR PROTRUSION
  SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
  5. DIMENSION K DOES NOT INCLUDE
  DAMBAR PROTRUSION. ALLOWABLE
  DAMBAR PROTRUSION SHALL BE 0.08
  (0.003) TOTAL IN EXCESS OF THE K
  DIMENSION AT MAXIMUM MATERIAL
  CONDITION.
- 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
  7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	6.40	6.60	0.252	0.260
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026	BSC
Н	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40		0.252	BSC
M	0°	8°	0°	8°



#### PACKAGE DIMENSIONS

SOIC-20 WB **DW SUFFIX** CASE 751D-05 **ISSUE G** 



#### NOTES:

- DIMENSIONS ARE IN MILLIMETERS.
- INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
- PROTRUSION.

  MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

  DIMENSION B DOES NOT INCLUDE DAMBAR
  PROTRUSION. ALLOWABLE PROTRUSION
  SHALL BE 0.13 TOTAL IN EXCESS OF B

  DIMENSION AT MAXIMUM MATERIAL CONDITION

	MILLIMETERS			
DIM	MIN	MAX		
Α	2.35	2.65		
A1	0.10	0.25		
В	0.35	0.49		
C	0.23	0.32		
D	12.65	12.95		
Е	7.40	7.60		
е	1.27	BSC		
Н	10.05	10.55		
h	0.25	0.75		
L	0.50	0.90		
θ	0 °	7 °		

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